

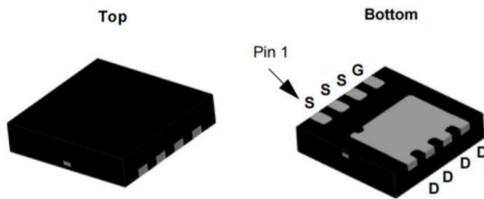
**Product Summary**

- $V_{DS}$  -150 V
- $I_{DS}$  -3A
- $R_{DS(ON)}$  (at  $V_{GS}=-10V$ ) <940mΩ

**Application**

- Active Clamp Switch
- Portable equipment and battery Powered systems
- Active Clamp in Intermediate DC/DC Power Supplies

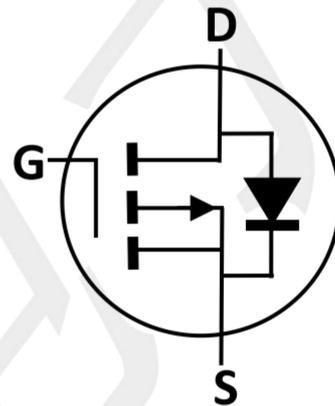
**Package and Pin Configuration**



**DFN3X3-8**

**Marking:**2523P

**Circuit diagram**



**Equivalent Circuit**

**Absolute Maximum Ratings** ( $T_A=25^\circ C$  unless otherwise noted) **Thermal Characteristic**

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	-150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	$T_C=25^\circ C$	-3
		$T_C=100^\circ C$	-1.6
Pulsed Drain Current	$I_{DM}$	-10	A
Total Power Dissipation	$P_{DTOT}$	7.7	W
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ C$
Storage Temperature Range	$T_{stg}$	-55 to +150	$^\circ C$

Note : When mounted on 1" square PCB (FR4 material).

PARAMETER	Symbol	Value	Unit
Junction-to-Ambient Thermal Resistance	$R_{thJA}$	62	$^\circ C/W$

**Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	BV <sub>DSS</sub>	-150	--	--	V
Gate-Source Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA	V <sub>GS(th)</sub>	-2	-3	-4	V
Gate-Source Leakage	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	I <sub>GSS</sub>	--	--	±100	nA
Zero Gate Voltage Drain Current	V <sub>DS</sub> = -120V, V <sub>GS</sub> =0V	I <sub>DSS</sub>	--	--	-1	μA
	V <sub>DS</sub> = -120V, T <sub>J</sub> =55°C		--	--	-10	μA
Drain-Source On-State Resistance (Note 1)	V <sub>GS</sub> = -10V, I <sub>D</sub> = -1A	R <sub>DS(on)</sub>	--	765	940	mΩ
	V <sub>GS</sub> = -10V, T <sub>J</sub> = 125°C		--	1500	--	
Forward Transconductance (Note 2)	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1A	g <sub>fs</sub>	--	2	--	S
<b>Dynamic (Note 2)</b>						
Total Gate Charge (Note 3)	V <sub>DS</sub> = -75V, I <sub>D</sub> = -3A, V <sub>GS</sub> = -10V	Q <sub>g</sub>	--	6.2	--	nC
Gate-Source Charge (Note 3)		Q <sub>gs</sub>	--	1.4	--	
Gate-Drain Charge (Note 3)		Q <sub>gd</sub>	--	3.3	--	
Input Capacitance	V <sub>DS</sub> = -25V, V <sub>GS</sub> = 0V, F= 1.0MHz	C <sub>iss</sub>	--	200	--	pF
Output Capacitance		C <sub>oss</sub>	--	60	--	
Reverse Transfer Capacitance		C <sub>rss</sub>	--	10	--	
<b>Switching</b>						
Turn-On Delay Time (Note 3)	V <sub>DD</sub> = -75V, I <sub>D</sub> = -3A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> = 25Ω	t <sub>d(on)</sub>	--	15	--	nS
Rise Time (Note 3)		t <sub>r</sub>	--	11	--	
Turn-Off Delay Time (Note 3)		t <sub>d(off)</sub>	--	19	--	
Fall Time (Note 3)		t <sub>f</sub>	--	13	--	
<b>Source-Drain Diode Ratings and Characteristics (Note 2)</b>						
Forward Voltage	V <sub>GS</sub> = 0V, I <sub>F</sub> = -3A	V <sub>SD</sub>	--	-0.8	-1.2	V
Continuous Source Current	Integral reverse diode in the MOSFET	I <sub>S</sub>	--	--	-3	A
Pulsed Current (Note 1)		I <sub>SM</sub>	--	--	-10	A

Notes:

1. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
2. Guaranteed by design, not subject to production testing.
3. Independent of operating temperature

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

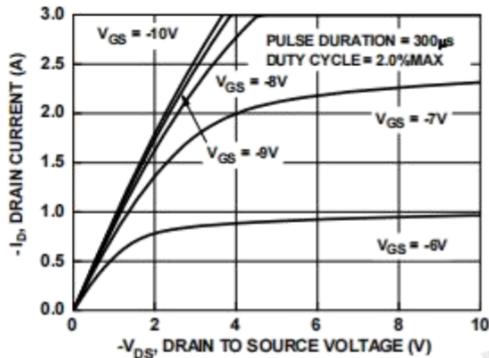


Figure 1. On-Region Characteristics

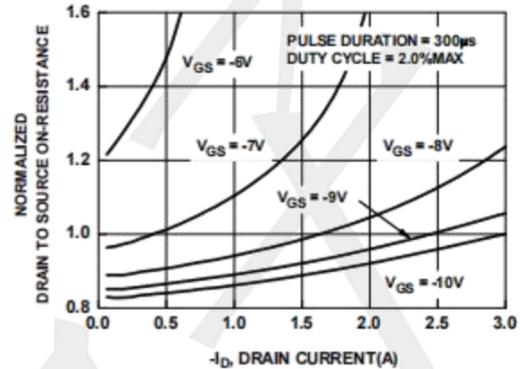


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

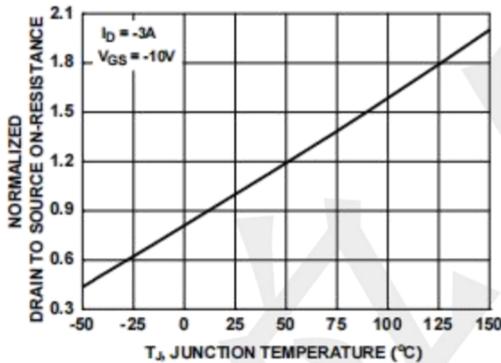


Figure 3. Normalized On-Resistance vs Junction Temperature

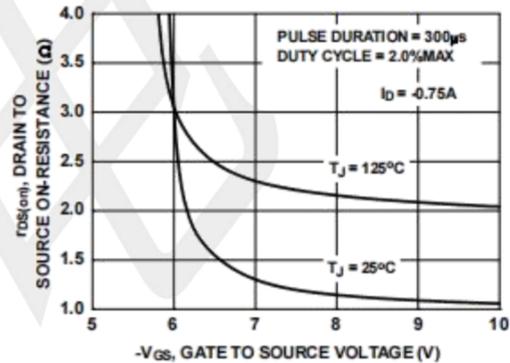


Figure 4. On-Resistance vs Gate to Source Voltage

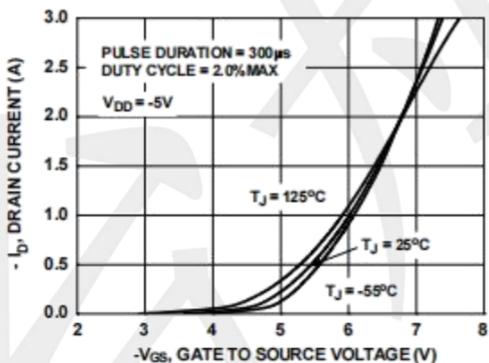


Figure 5. Transfer Characteristics

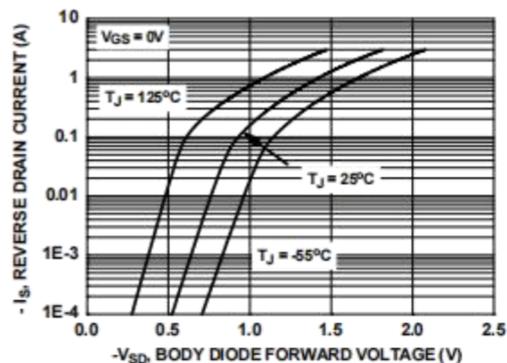
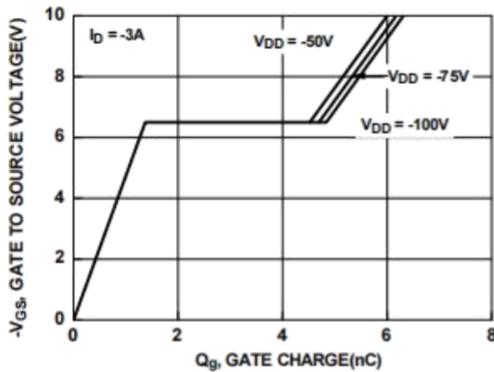
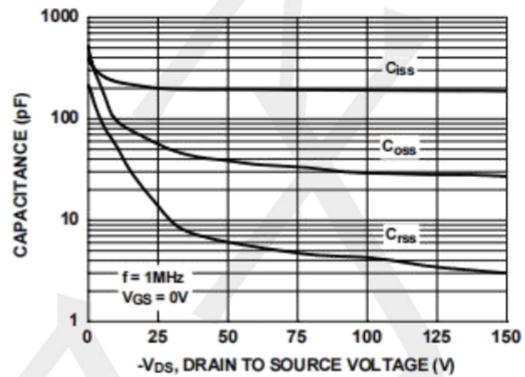


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

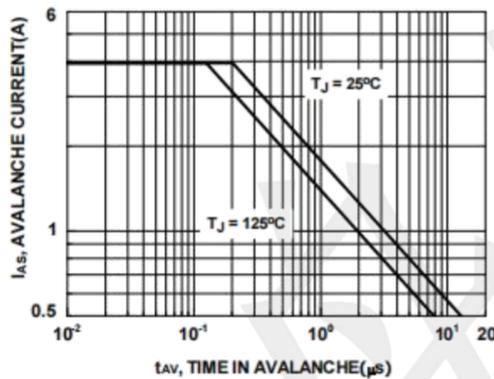
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



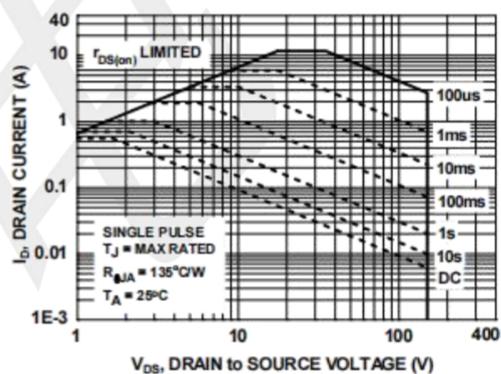
**Figure 7. Gate Charge Characteristics**



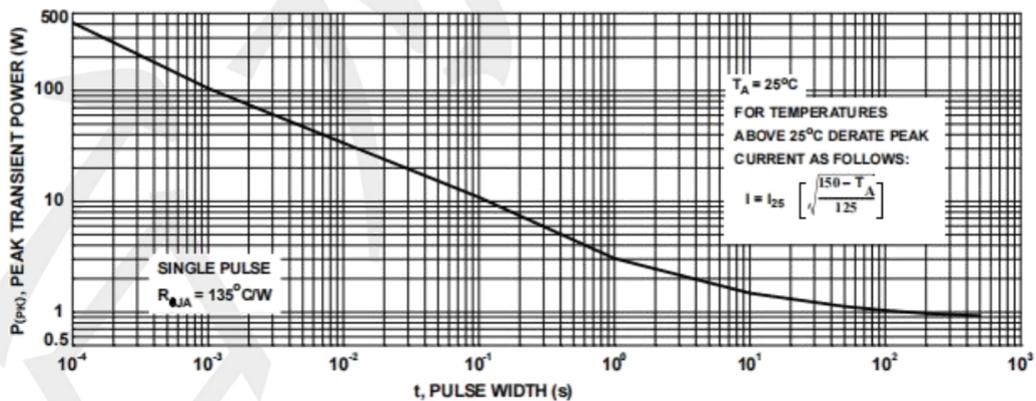
**Figure 8. Capacitance vs Drain to Source Voltage**



**Figure 9. Unclamped Inductive Switching Capability**



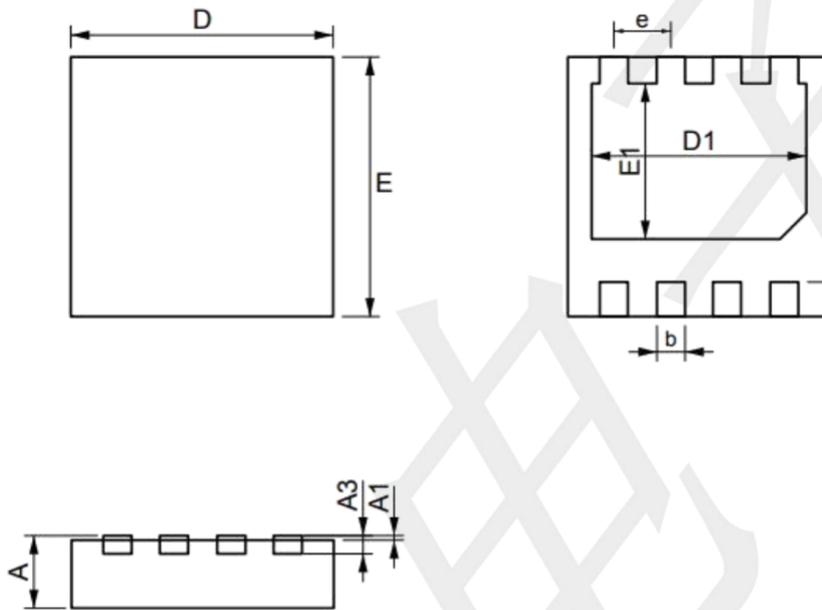
**Figure 10. Forward Bias Safe Operating Area**



**Figure 11. Single Pulse Maximum Power Dissipation**

\* The power dissipation PD is based on T<sub>J(max)</sub> = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**DFN3X3-8 Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF		0.008REF	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.200MIN.		0.008MIN.	
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019